

# **Product Change Notification - JAON-22CQBF728**

Date:

25 May 2020

**Product Category:** 

8-bit Microcontrollers

**Affected CPNs:** 



#### **Notification subject:**

CCB 3702.003 and 3702.004 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material for selected ATML AT90CAN64, AT90CAN128, AT90PWM81xx and ATMEGA168PA device families available in 32L VQFN (5x5x0.9mm) and 64L VQFN (9x9x0.9mm) packages at NSEB assembly site.

#### **Notification text:**

### **PCN Status:**

Final notification

## PCN Type:

Manufacturing Change

### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

### **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material for selected ATML AT90CAN64, AT90CAN128, AT90PWM81xx and ATMEGA168PA device families available in 32L VQFN (5x5x0.9mm) and 64L VQFN (9x9x0.9mm) packages at NSEB assembly site.

### **Pre Change:**

For 32L VQFN: Using gold (Au) bond wire, 8600 die attach, G770HCD mold compound and A194 lead frame material.

For 64L VQFN: Using gold (Au) bond wire, 8200T die attach, G770HCD mold compound and EFTEC 64T lead frame material.

#### **Post Change:**

For both 32L and 64L VQFN: Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, G700LTD mold compound and EFTEC 64T lead frame material.

Pre and Post Change Summary:

		Pre Change	Post Change			
Assembly Site		UTAC Thai Limited LTD.	UTAC Thai Limited LTD.			
		(NSEB)	(NSEB)			
Wire material		Au	CuPdAu			
Die attach material	64L VQFN	8200T	8600			
	32L VQFN	8600	8000			
Molding compound material		G770HCD	G700LTD			
Lead frame material	64L VQFN	EFTEC 64T	EFTEC 64T			
	32L VQFN	A194	LI 1LC 041			

Impacts to Data Sheet:

None

**Change Impact:** 

None



## Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

### **Change Implementation Status:**

In Progress

## **Estimated First Ship Date:**

July 10, 2020 (date code: 2028)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### Time Table Summary:

	May 2020				->	July 2020					
Workweek	18	19	20	21	22		27	28	29	30	31
Qual Report Availability					X						
Final PCN Issue Date					Χ						
Estimated Implementation								Y			
Date								^			

### **Method to Identify Change:**

Traceability code

## **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

### **Revision History**:

May 25, 2020: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachment(s):

PCN JAON-22CQBF728 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers  $\overline{(CPN)}$ 

ATMEGA168PA-MU

ATMEGA168PA-MUR

AT90PWM81EP-16MN

AT90PWM81OS-B16MNR

AT90CAN64-16MU

AT90CAN64-16MU-HCM

AT90CAN64-16MUR

AT90CAN128-16MU

AT90CAN128-16MUR

Date: Monday, May 25, 2020